

1. A liquid-crystal display unit
comprising:

a first board having a signal line, a scanning line and a pixel electrode;

a second board having a common electrode,
the second board opposing said first board;

a liquid-crystal layer provided between said first board and said second board; and

15 a third board having at least one of a
signal-line driver driving said signal line and a
scanning-line driver driving said scanning line, the
third board being separate from said first board and
said second board.

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2. The liquid-crystal display unit as claimed in claim 1, wherein said third board is formed of a same material as said first board.

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3. The liquid-crystal display unit as claimed in claim 1, wherein said third board is connected to said first board by a flexible cable.

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4. The liquid-crystal display unit as

1-5	board	10
1st & 2nd	board	15
2nd	not divided	20

claimed in claim 1, wherein said third board is connected to said first board by a wire bonding.

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5. The liquid-crystal display unit as claimed in claim 1, wherein said third board is connected to said first board by a flip-chip bonding.

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6. A method of manufacturing a liquid-crystal display unit including: a first board having a signal line, a scanning line and a pixel electrode; a second board having a common electrode, the second board opposing said first board; and a liquid-crystal layer provided between said first board and said second board, the method comprising the steps of:

forming said signal line, said scanning line, said pixel electrode, and at least one of a signal-line driver driving said signal line and a scanning-line driver driving said scanning line on a same substrate; and

dividing said same substrate into said first board and a third board having at least one of said signal-line driver and said scanning-line driver.

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7. The method as claimed in claim 6, wherein said step of forming forms said signal line, said scanning line, said pixel electrode, and at

least one of said signal-line driver and said scanning-line driver in a same process.

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8. The method as claimed in claim 6, further comprising the step of connecting said third board to said first board by a flexible cable.

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9. The method as claimed in claim 6, further comprising the step of connecting said third board to said first board by a wire bonding.

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10. The method as claimed in claim 6, further comprising the step of connecting said third board to said first board by a flip-chip bonding.